

Laminated sheet for printed circuit board - comprises woven glass fabric surface layers filled with brucite, alumina and kaolin, and non-woven glass fabric interlayer

Patent Assignee: SUMITOMO BAKELITE CO LTD (SUMB)

Number of Countries: 001 Number of Patents: 001

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
JP 10146916	A	19980602	JP 96305116	A	19961115	199832 B

Priority Applications (No Type Date): JP 96305116 A 19961115

Patent Details:

Patent No	Kind	Lan	Pg	Main IPC	Filing Notes
JP 10146916	A		4	B32B-017/04	

Abstract (Basic): JP 10146916 A

Laminated sheet for a printed circuit comprises: surface layers having woven glass fabric impregnated with a resin contg. 100 wt. parts of a thermosetting resin and 30-300 wt. parts of an inorganic filler. The intermediate layer consists of a nonwoven glass fabric impregnated with a resin contg. 100 wt. parts of a thermosetting resin and 60-600 wt. parts of an inorganic filler. The inorganic filler of the surface layers contains 15-250 wt. parts of powdered brucite and 10-150 wt. parts of alumina or kaolin clay for every 100 wt. parts of the thermosetting resin.

ADVANTAGE - The laminated sheet for a printed circuit has resistance to flame and soldering which is equivalent to that of the conventional composite laminated sheet with a halogen cpd. but generates little smoke and harmful gas.

Dwg.0/0

Title Terms: LAMINATE; SHEET; PRINT; CIRCUIT; BOARD; COMPRISE; WOVEN; GLASS ; FABRIC; SURFACE; LAYER; FILLED; BRUCITE; ALUMINA; KAOLIN; NON; WOVEN; GLASS; FABRIC; INTERLAYER

Index Terms/Additional Words: PCB

Derwent Class: A85; L03; P73; V04

International Patent Class (Main): B32B-017/04

International Patent Class (Additional): B32B-027/04; B32B-027/20; C08J-005/24; C08K-003/20; C08L-101/00; H05K-001/03

File Segment: CPI; EPI; EngPI

?